



Main Features

- Support 9th and 8th Gen Intel® Core™ i7/i5/i3 processor
- Intel® PCH Q370
- Intel® integrated UHD 630 graphic engine
- Support 3 independent 4K@ 60Hz display output
- Support extended temperature -20~60°C
- 3 x HDMI 2.0, 6 x USB 3.0, 2 x GbE LAN, 1 x Line-out, 1 x Mic-in
- 1 x RS-232/422/485, 3 x RS232
- 3 x M.2 socket Key B/E/M
- Support 1 x 2.5" SATA HDD Space
- Fanless design

Product Overview

Powered by the 9th and 8th generation Intel® Core™ processor series and Intel® 300 Series chipset integrated graphics controller, the NDiS B560-Q fanless embedded system can handle powerful multimedia content. In addition, the NDiS B560-Q can be operated in an extended operating temperature range between -20 to 60 Celsius degree, with three 4K2K independent display output and rich connectives including Wi-Fi and 4G, 5G support, the NDiS B560-Q can fully satisfy customer's expectation and therefore be used in both in-door and out-door applications such as self-service KIOSK, vending machine, hospitality, and passenger information at outdoor bus station.

Specifications

CPU Support

- 9th and 8th Gen Intel® Core™ i7/i5/i3 LGA socket type processor, up to 35W
 - Core™ i7-9700TE, 8 Core, 1.8GHz, 12M Cache
 - Core™ i5-9500TE, 6 Core, 2.2GHz, 9M Cache
 - Core™ i3-9100TE, 4 Core, 2.2GHz, 6M Cache
 - Core™ i7-8700T, 6 Core, 2.4GHz, 12M Cache
 - Core™ i5-8500T, 6 Core, 2.1GHz, 9M Cache
 - Core™ i3-8100T, 4 Core, 3.1GHz, 6M Cache
- 2 x USB 3.0
- 4 x DB9 for COM1~COM4
 - COM1: RS-232/422/485
 - COM2~4: RS232
- 2 x Antenna hole

Chipset

- Intel® PCH Q370

Graphics

- Intel® UHD graphics 630 series

Main Memory

- 2 x 260-pin SO-DIMM sockets, support DDR4 2666 MHz non-ECC, unbuffered memory up to 32G (single socket max. 16GB)

I/O Interface-Front

- 1 x Power button with LED
- 1 x Power LED, 1 x HDD LED
- 1 x Reset switch

I/O Interface-Rear

- +12V DC-in
- 3 x HDMI 2.0
- 4 x USB 3.0
- 1 x Intel® I219-LM GbE LAN port
- 1 x Intel® I226-IT 2.5G Ethernet LAN port
- 1 x Mic-in, 1 x Line-out
- 2 x Antenna hole

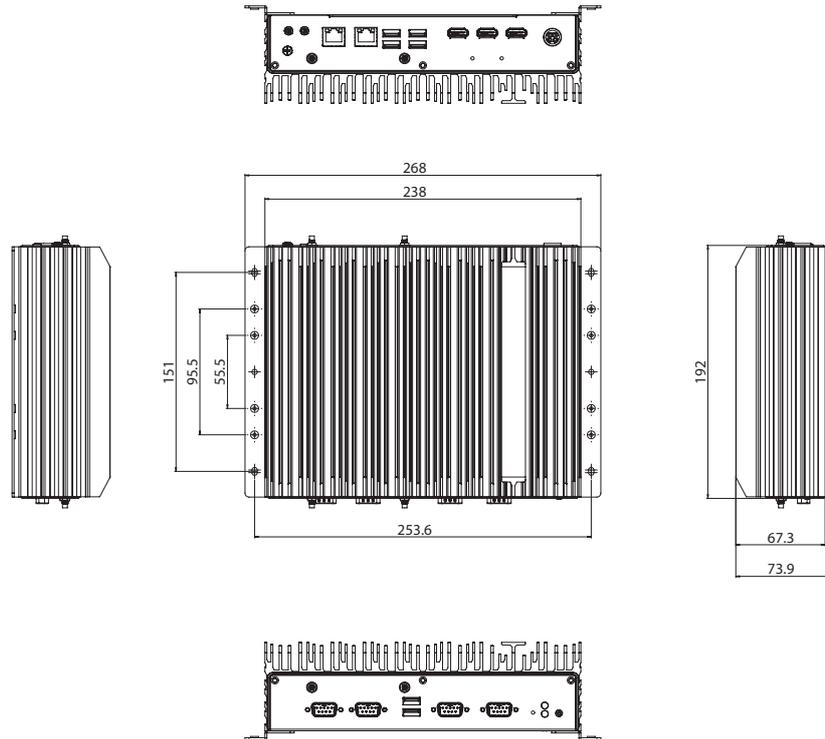
I/O Interface-Internal

- 8CH GPIO support 4 x GPO and 4 x GPI
- Onboard TPM 2.0

Storage

- 1 x SATA 2.5" HDD/SSD storage space
- 1 x M.2 2280 (SATA, PCIe x4)/2242 (by request) Key M socket

Dimension Drawing



Expansion

- 1 x M.2 2230 Key E (PCIe x2), support optional Wi-Fi modules
- 1 x M.2 3042/3052 Key B (SATA, USB 3.0), support optional 3G, 4G or 5G modules
- 1 x SIM slot

Power Supply

- 1 x External 96W AC/DC power adapter
- Input: 100VAC to 240VAC
- Output: DC+12VDC

Environment

- Operating temperature: -20°C to 60°C ambient with 0.7m/s air flow
- Storage temperature: -20°C to 80°C
- Humidity: 10 to 95% (non-condensing)

Certification

- CE Approval (EN55032/55035)
- FCC Class A (Part 15B)

Dimensions

- 238mm (W) x 192mm (D) x 67.29mm (H) w/o bracket

Operating System Support

- Win10/11/Linux

Package Information

- 1 pc/carton
- G.W: 5kgs
- Dimension: 420 x 275 x 127mm

Ordering Information

- **NDIS B560-Q (P/N: 10W00B56007X0)**
9th and 8th Gen Intel® Core™ processor (up to 35W) fanless system
Intel® Q370 chipset